



PPAP

Technical

Specification

Revision #	Date	Changes	Responsible(s)
00	14/03/2018	New Release	F. Poggi
01	25/02/2020	Added: Technical Bulletin, Certificate of Conformance in Class 1 (page 3); Added Packaging Reference in Classes 1 and 2 (page 3); Added Statistical Process Control (SPC) in Classes 2 and 3 (pages 3 and 4);	F. Poggi

1. PURPOSE

The purpose of this specification is to report all the documents required by ZAPI GROUP (hereinafter called ZAPI) for the PPAP submission.

2. APPLICABILITY

This document applies to all the ZAPI Suppliers.

3. CATEGORIES

Class 1	Class 2	Class 3
Catalogue parts (e.g. bulk material, standard electronic components)	Parts on ZAPI drawing (e.g. heatsinks, plastic covers, gaskets, special parts)	PCB / PCBA (printed circuit boards, printed circuit boards assembly)

4. DOCUMENTATION REQUIRED

Class	Documents
1	• Samples • Black/Grey Lists compliance • Technical Bulletin (e.g. datasheet) • Certificate of Conformance • Packaging Reference
2	• Samples • Black/Grey Lists compliance • Part Submission Warrant (PSW) • Process Flowchart • Process FMEA • Process Control Plan • Dimensional Inspection • Statistical Process Control (SPC) • Raw Material Certification • Chemical Characterization (when applicable e.g. Surface treatments) • Packaging Reference

3	PCB	• Samples • Black/Grey Lists compliance • Part Submission Warrant (PSW) • Process Flowchart • Process FMEA • Process Control Plan • Dimensional Inspection • Statistical Process Control (SPC) • Plating Thickness Report • Wettability Report • Raw Material Certification
	PCBA	• Samples • Black/Grey Lists compliance • Part Submission Warrant (PSW) • Process Flowchart • Process FMEA • Process Control Plan • Statistical Process Control (SPC) • In-Circuit Test Coverage (Components/Nets)

Note: in special cases, any additional information may be required by ZAPI according to ZPSF-2017-0008 – Supplier Quality Book.